

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16419	
1.3 Title of PCN	Amkor ATJ (Japan) additional assembly line for STM32H74x & STM32H75x listed products in LQFP20x20 and LQFP14x14 packages	
1.4 Product Category	STM32H742x, STM32H743x, STM32H750 and STM32H753x.	
1.5 Issue date	2026-07-09	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Amkor ATJ (Japan)

4. Description of change

	Old	New
4.1 Description	Current assembly sites (depending on package): - ST Muar (Malaysia) Copper Alloy wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire, - AMKOR ATP (Philippine) Gold wire. - AMKOR ATP (Philippine) Copper Palladium wire. You may refer to 16419_Additional information.pdf document for further details.	Current assembly sites: (depending on package) : - ST Muar (Malaysia) Copper Alloy wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire, - AMKOR ATP (Philippine) Gold wire. - AMKOR ATP (Philippine) Copper Palladium wire. Additional assembly site for extended capacity: - Amkor ATJ (Japan) Copper Palladium wire .
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Change is visible on the marking Assembly Site code . - 99 : ST MUAR (Malaysia) - AA : ASE KaoHsiung (Taiwan) - 7B : AMKOR ATP (Philippines) - 6Z : AMKOR ATJ (Japan) Please refer to PCN 16419_Additional information.pdf document for further details.
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7. Timing / schedule

7.1 Date of qualification results	2026-10-16
7.2 Intended start of delivery	2026-10-28

7.3 Qualification sample available?	Upon Request
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8. Qualification / Validation			
8.1 Description	16419 MDRF-GPAM-RER2517 PCN16419 ATJ3 LQFP14x14 to 20X20 CuPd wires STM32-reliability evaluation plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-07-09

9. Attachments (additional documentations)
16419 Public product.pdf 16419 MDRF-GPAM-RER2517 PCN16419 ATJ3 LQFP14x14 to 20X20 CuPd wires STM32- reliability evaluation plan.pdf 16419 _Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H742VIT6	
	STM32H742ZGT6	
2980947	STM32H750VBT6	

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Public Products List

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PCN Title : Amkor ATJ (Japan) additional assembly line for STM32H74x & STM32H75x listed products in LQFP20x20 and LQFP14x14 packages

PCN Reference : EMBEDDED PROCESSING/26/16419

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32H750VBT6TR	STM32H743ZGT6	STM32H753VIT6
STM32H743VGT6	STM32H743VIT6TR	STM32H750VBT6
STM32H750ZBT6	STM32H742VGT6	STM32H743VIT6
STM32H742VIT6TR	STM32H742ZIT6	STM32H742VIT6
STM32H742ZGT6	STM32H742VGT6TR	STM32H743ZIT6
STM32H743ZIT6TR	STM32H753ZIT6	

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PRODUCT/PROCESS CHANGE NOTIFICATION

PCN16419 – Additional information

Amkor ATJ (Japan) additional assembly line for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 14x14 packages.

MRDF – General Purpose and Automotive Microcontrollers (GPAM)

What are the changes?

- STM32H75x/74x products have been transferred to Amkor ATJ (Japan) in TQFP20x20 and TQFP14x14 packages.
- The design database remains the same. No change in the silicon version.

Changes are described in the tables below:

Table 1 : Back-End assembly Sites for LQFP 100L 14x14 packages

LQFP 100L 14x14	Existing back-end line				Added back-end line
Assembly site	ST Muar (Malaysia)	ASE Kaohsiung (Taiwan)	AMKOR ATP (Philippines)		AMKOR ATJ (Japan)
Molding Compound ⁽¹⁾	EME-G700LS	EME-G631SH	EME-G631SHQ		EME-G660B
Die Attach material	ABLESTIK ABP8302	EN4900G	Evertech AP4200	ABLESTIK 3230	
Bonding wire	Copper Alloy 0.8mil	Copper Palladium 0.8mil	Gold 0.8mil	Copper Palladium 0.8mil	

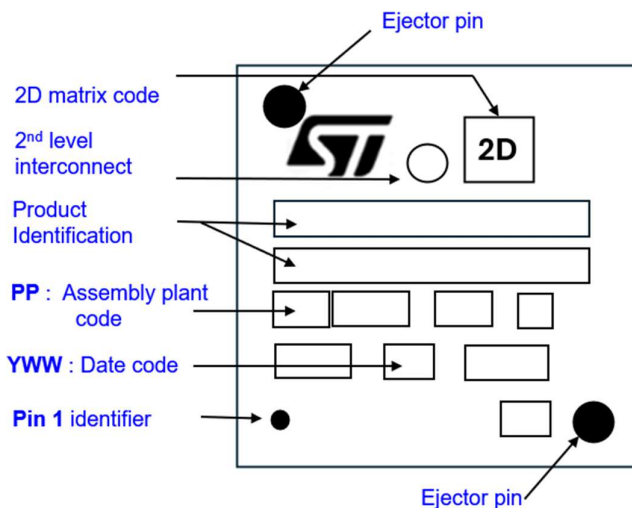
Table 2 : Back-End assembly Sites for LQFP 144L 20x20 packages

LQFP 144L 20x20	Existing back-end line			Added back-end line
Assembly site	ASE Kaohsiung (Taiwan)	AMKOR ATP (Philippines)		AMKOR ATJ (Japan)
Molding Compound ⁽¹⁾	EME-G631SH	EME-G631SHQ		EME-G660B
Die Attach material	EN-4900G-	Evertech AP4200	ABLESTIK 3230	
Bonding wire	Copper Palladium 0.8mil	Gold 0.8mil	Copper Palladium 0.8mil	

⁽¹⁾ Package darkness or chromaticity may change depending on molding compound.

How can the change be seen?

The standard marking fields example below
for **LQFP 144L 20x20** package



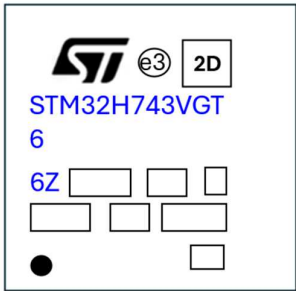
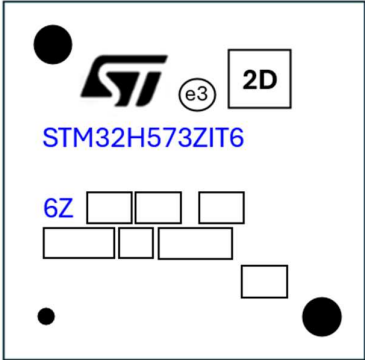
Pin1 identifier may change in terms of size and positioning however remaining near pin1's edge.
Marking position and size may be different upon assembly site, without any loss of information.

Package top view marking examples as below

Table 3: Marking fields

	Existing Back-end			Added Back-End Site
Assembly sites	ST MUAR (Malaysia)	ASE KaoHsiung (Taiwan)	AMKOR ATP (Philippines)	Amkor ATJ (Japan)
PP : Assembly plant code	"99"	"AA"	"7B"	"6Z"

Table 2: Marking Example with Commercial product

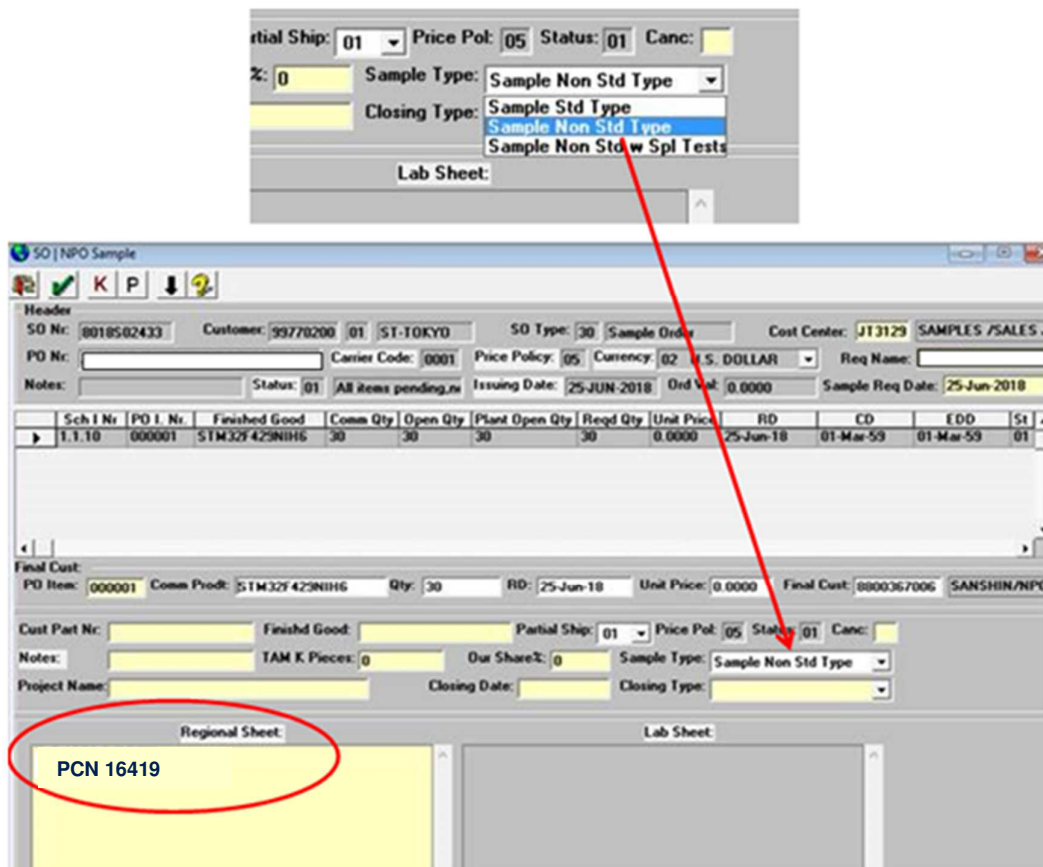
Package example	Amkor ATJ (Japan)
LQFP 14x14 100L (ie: STM32H743VGT6)	 The diagram shows a square package with a grid of pins. Markings include the ST logo, a circled 'e3', a '2D' box, the part number 'STM32H743VGT' in blue, and the suffix '6' in blue. There are also '6Z' and several empty boxes for additional markings.
LQFP 20x20 144L (ie: STM32H742ZIT6)	 The diagram shows a square package with a grid of pins. Markings include the ST logo, a circled 'e3', a '2D' box, the part number 'STM32H573ZIT6' in blue, and the suffix '6' in blue. There are also '6Z' and several empty boxes for additional markings. Two large black circles are present at the top-left and bottom-right corners of the package area.

Please refer to product **DataSheet** or Technical Note **TN1433** for package marking details.

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu).
- insert the PCN number "**PCN16419**" into the NPO Electronic Sheet/**Regional Sheet**.
- request sample(s) through Notice tool, indicating a single Commercial Product for each request.



The screenshot displays the 'NPO Sample' software interface. At the top, a dropdown menu for 'Sample Type' is open, showing options: 'Sample Std Type', 'Sample Non Std Type' (highlighted), and 'Sample Non Std w Spl Tests'. A red arrow points from this menu to the 'Sample Type' field in the main form. The main form includes fields for 'SO No.', 'Customer', 'SO Type', 'Cost Center', 'PO No.', 'Carrier Code', 'Price Policy', 'Currency', 'Req Name', 'Status', 'Issuing Date', 'Ord Val', and 'Sample Req Date'. Below these is a table with columns: 'Sch I Nr', 'PO I. Nr', 'Finished Good', 'Comm Qty', 'Open Qty', 'Plant Open Qty', 'Reqd Qty', 'Unit Price', 'RD', 'CD', 'EOD', and 'St'. The table contains one row with data. Below the table, there are fields for 'Final Cust', 'PO Item', 'Comm Prod', 'Qty', 'RD', 'Unit Price', and 'Final Cust'. At the bottom, there are fields for 'Cust Part Nr', 'Finishd Good', 'Partial Ship', 'Price Pol', 'Status', 'Canc', 'Notes', 'TAM K Pieces', 'Our Share%', 'Sample Type', 'Closing Date', and 'Closing Type'. The 'Regional Sheet' tab is selected, and the text 'PCN 16419' is entered in the 'Notes' field, which is circled in red.

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STRIVE
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MDRF-GPAM-RER2517 PCN16419 ATJ3 LQFP14x14 to 20X20 CuPd wire

Reliability Evaluation Plan

30 June 2026

MDRF GPAM Q&R

MDRF-GPAM-RER2517 PCN16419

ATJ3 LQFP14x14 to 20X20 CuPd wire

Package Test Vehicles

Package line	Assembly Line	Package	Device (RawLine Code)	Diffusion Process/Plant	Number of Reliability Lots	Reliability
QFP	LQFP14x14	100L	1L*450	E40/Crolles	1	Full reliability
	LQFP20x20	144L	1A*450	E40/Crolles	1	Full reliability
				E40/HHG	1	Full reliability
	LQFP14x14	100L	1L*450	M40/Samsung Foundry	1	CDM
	LQFP20x20	144L	1A*450	M40/Samsung foundry	1	Full reliability

Qualification strategy:

- ATJ3 LQFP copper wire assembly line will be qualified with 5 package reliability lots from representative test vehicles of STM32H562x, STM32H563x, STM32H573x, STM32H74x and STM32H75x products:
 - 1 Full package reliability lot of LQFP14x14 with E40 Crolles
 - 1 Full package reliability lot of LQFP20x20 with E40 Crolles
 - 1 Full package reliability lot of LQFP20x20 with E40 HHG
 - 1 Full package reliability lot of LQFP20x20 with M40 Samsung Foundry
 - 1 CDM package lot of LQFP14x14 with M40 Samsung Foundry
- E40 Crolles/HHG and M40 Samsung Foundry technologies will be qualified in ATJ3 for LQFP14x14 and LQFP20x20 package size
- Refer to details in above and next tables.

MDRF-GPAM-RER2517 PCN16419

ATJ3 LQFP14x14 to 20X20 CuPd wire

Reliability plan

(*) tests performed after preconditioning

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Number of lot
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	231	4
Uhast(*)	UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	130°C, 85%RH, 2.3 atm	96h	77	4
TC(*)	Thermal Cycling JESD22 A104	-65°C +150°C	500cy	77	4
THB(*)	Biased temperature & humidity stress JESD22 A101	85°C, 85% RH bias	1000h	77	4
HTSL	High Temperature Storage Life JESD22 A103	150°C	1000h	77	4
Construction analysis	ST internal specifications	Construction analysis including Ball shear, pull test, IMC inspection , ST internal specification	NA	50	4
ESD	ESD Charge Device Model JEDEC JS-002	500V	No failure	3	5

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